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| Title of Change: | Transfer of ECH8320-TL-H from ON Semiconductor wafer fab in Gifu, Japan to United Microelectronics Corporation (UMC) wafer fab in Taiwan. |
| Proposed first ship date: | 27 April 2017 |
| Contact information: | Contact your local ON Semiconductor Sales Office or <Osamu.Akaki@onsemi.com> |
| Samples: | Contact your local ON Semiconductor Sales Office |
| Additional Reliability Data: | Contact your local ON Semiconductor Sales Office or <Yasuhiro.Igarashi@onsemi.com> |
| Type of notification: | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>. |
| Change Part Identification: | Affected products will be identified with date code. |
| Change category: | <input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____ |
| Change Sub-Category(s): | <input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____ |
| Sites Affected: | <input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s): ON Semiconductor, Gifu, Japan <input checked="" type="checkbox"/> External Foundry/Subcon site(s) UNITED MICROELECTRONICS CORP |
| Description and Purpose: | <p>This Final Process Change Notification is to announce the transfer of products from the ON semiconductor wafer fabrication sites located in Gifu Japan to United Microelectronics Corporation (UMC) wafer fab at No.3, Li-Hsin 2nd RD., Hsinchu Science Park, Hsinchu, Taiwan, R.O.C.</p> <p>The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications.</p> |



Reliability Data Summary:

QV DEVICE NAME: ECH8310-TL-H

PACKAGE: SOT-28 FL/ECH-8

| Test | Specification | Condition | Interval | Results |
|-------|---------------|----------------------------------|------------|---------|
| HTRB | JESD22-A108 | Ta=150°C, 100% max rated VDSS | 1,000 hrs | 0/22 |
| HTGB | JESD22-A108 | Ta=150°C, 100% max rated VGSS | 1,000 hrs | 0/22 |
| HTSL | JESD22-A103 | Ta= 150°C | 1,000 hrs | 0/22 |
| SSOL | JESD22-A108 | Tj= 150°C | 1,000 hrs | 0/22 |
| TC | JESD22-A104 | Ta= -55°C to +150°C | 100 cycles | 0/22 |
| AC | JESD22-A102 | Ta = 121°C, 100% RH, 15psig | 50 hrs | 0/22 |
| H3TRB | JESD22-A101 | 85°C, 85% RH, 80% max rated VDSS | 1,000 hrs | 0/22 |
| RS | JESD22- B106 | Solder Temp: 260±5°C | 10sec | 0/22 |

Electrical Characteristic Summary:

Electrical characteristics are not impacted

List of affected Standard Parts:

| Part Number | Qualification Vehicle |
|--------------|-----------------------|
| ECH8320-TL-H | ECH8310-TL-H |